

Electronic Patent Application Fee Transmittal

Application Number:	10664982			
Filing Date:	17-Sep-2003			
Title of Invention:	Packaging system for die-up connection of a die-down oriented integrated circuit			
First Named Inventor/Applicant Name:	David Chong Sook Lim			
Filer:	Edwin H. Paul/Jonathan DeBlois			
Attorney Docket Number:	112055-0040P1			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Notice of appeal	1401	1	510	510
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				510